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From: Texas Instruments Incorporated  
Facsimile: 972-917-4418  
Phone: 972-271-1176

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Celli et al.

Art Unit: 1765

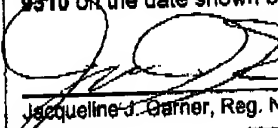
Serial No.: 09/599,718

Examiner: Brown, C.

Filing Date: 06/22/00

Docket No.: TI-29276

Title: PROCESS FLOW FOR DUAL DAMASCENE INTERCONNECT  
STRUCTURES

CERTIFICATION OF FACSIMILE TRANSMISSION	
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## FACSIMILE COVER SHEET

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NAME OF INVENTOR(S):	
Celli	
TITLE OF INVENTION:	
Process Flow for Dual Damascene Interconnect	
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Texas Instruments Incorporated  
PO Box 655474, M/S 3999  
Dallas, TX 75074

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Request for Reconsideration under 37 CFR 1.115

Assistant Commissioner of Patents  
Washington, DC 20231

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Dear Sir:

The following remarks are offered in response to the Examiner's Office Action dated 08/21/01. They are respectfully submitted as a full and complete response to that Action.

**REMARKS**

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.

Claims 1-9 are pending in this case.

The Examiner rejected claims 1-9 under 35 U.S.C. §103(a) as being unpatentable over Jang et al. (U.S. Pat. No. 6,019,906) in view of Chen et al. (U.S. Pat. No. 6,211,061).